SCAS284G - JANUARY 1993 - REVISED OCTOBER 1998

- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Typical V<sub>OLP</sub> (Output Ground Bounce)  $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)  $> 2 V at V_{CC} = 3.3 V, T_A = 25^{\circ}C$
- Inputs Accept Voltages to 5.5 V
- **Package Options Include Plastic** Small-Outline (D), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) **Packages**

#### D, DB, OR PW PACKAGE (TOP VIEW) 14 VCC 1A 1B 🛮 13 1 1C 2A $\prod$ 3 12∏ 1Y 2B 🛮 11 3C 2C 10 3B 2Y 9 3A 8∏ 3Y **GND**

### description

This triple 3-input positive-NAND gate is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74LVC10A performs the Boolean function  $Y = \overline{A \cdot B \cdot C}$  or  $Y = \overline{A} + \overline{B} + \overline{C}$  in positive logic.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

The SN74LVC10A is characterized for operation from -40°C to 85°C.

#### **FUNCTION TABLE** (each gate)

INPUTS			OUTPUT
Α	В	С	Y
Н	Н	Н	L
L	X	Χ	Н
Χ	L	Χ	Н
Х	Χ	L	Н

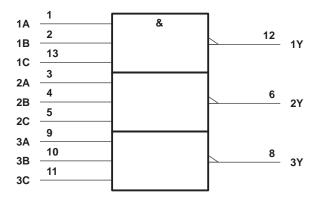


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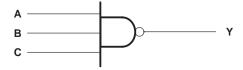


### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

#### logic diagram, each gate (positive logic)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>		
Input voltage range, V <sub>I</sub> (see Note 1)		
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)		
Input clamp current, $I_{IK}$ ( $V_I < 0$ )		
Output clamp current, $I_{OK}$ ( $V_O < 0$ )		
Continuous output current, I <sub>O</sub>		
Continuous current through V <sub>CC</sub> or GND		
Package thermal impedance, θ <sub>JA</sub> (see Note 3):		
r ackage mermai impedance, oja (see Note 3).		
	DB package	
	PW package	
Storage temperature range, T <sub>sto</sub>		–65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The value of  $V_{\hbox{CC}}$  is provided in the recommended operating conditions table.
  - 3. The package thermal impedance is calculated in accordance with JESD 51.



### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
\/oo	Supply voltage		1.65	3.6	V	
VCC	Supply voltage	Data retention only	1.5		V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V <sub>0</sub>	CC		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>		
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$				
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
VI	Input voltage		0	5.5	V	
٧o	Output voltage		0	Vcc	V	
		V <sub>CC</sub> = 1.65 V		-4		
	High-level output current	V <sub>CC</sub> = 2.3 V		-8	—   mA	
ЮН		V <sub>CC</sub> = 2.7 V		-12		
		V <sub>CC</sub> = 3 V		-24		
lOL		V <sub>CC</sub> = 1.65 V		4		
	Laurianal antent annual	V <sub>CC</sub> = 2.3 V		8	mΛ	
	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA	
	V <sub>CC</sub> = 3 V			24		
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	v <sub>cc</sub>	MIN TYPT	MAX	UNIT
	$I_{OH} = -100 \mu\text{A}$	1.65 V to 3.6 V	V <sub>CC</sub> -0.2		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2		
Vou	$I_{OH} = -8 \text{ mA}$	2.3 V	1.7		V
VOH	I <sub>OH</sub> = -12 mA	2.7 V	2.2		V
	10H = -12 111A	3 V	2.4		
	I <sub>OH</sub> = -24 mA	3 V	2.2		
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V		0.2	
	I <sub>OL</sub> = 4 mA	1.65 V		0.45	
V <sub>OL</sub>	I <sub>OL</sub> = 8 mA	2.3 V		0.7	V
	I <sub>OL</sub> = 12 mA	2.7 V		0.4	
	I <sub>OL</sub> = 24 mA	3 V		0.55	
lį	V <sub>I</sub> = 5.5 V or GND	3.6 V		±5	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		10	μΑ
ΔlCC	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V		500	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V	5	·	pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C.



SCAS284G - JANUARY 1993 - REVISED OCTOBER 1998

# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	
<sup>t</sup> pd	A	Y	13.8	1	7.8		5.8	1	4.9	ns
t <sub>sk(o)</sub> †					·				1	ns

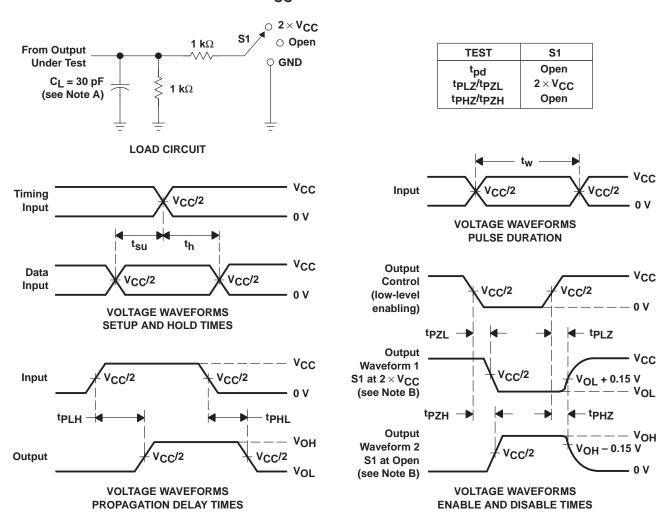
<sup>†</sup> Skew between any two outputs of the same package switching in the same direction

## operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
		CONDITIONS	TYP	TYP	TYP	ONIT
C <sub>pd</sub>	Power dissipation capacitance per gate	f = 10 MHz	9	10	11	pF



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

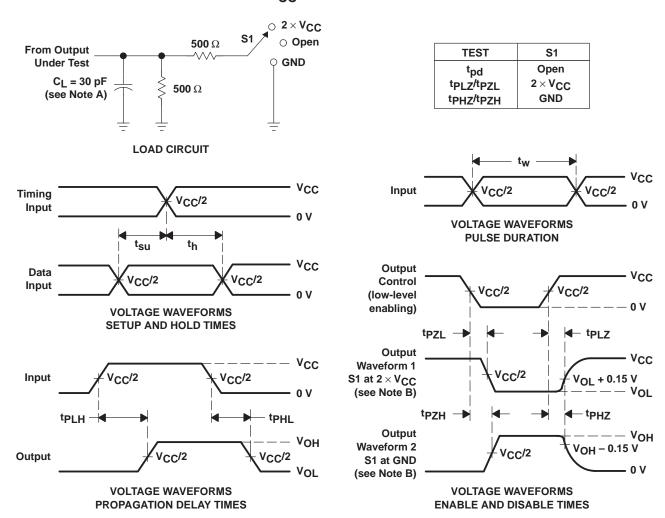


NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2 ns.  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.5 V $\pm$ 0.2 V



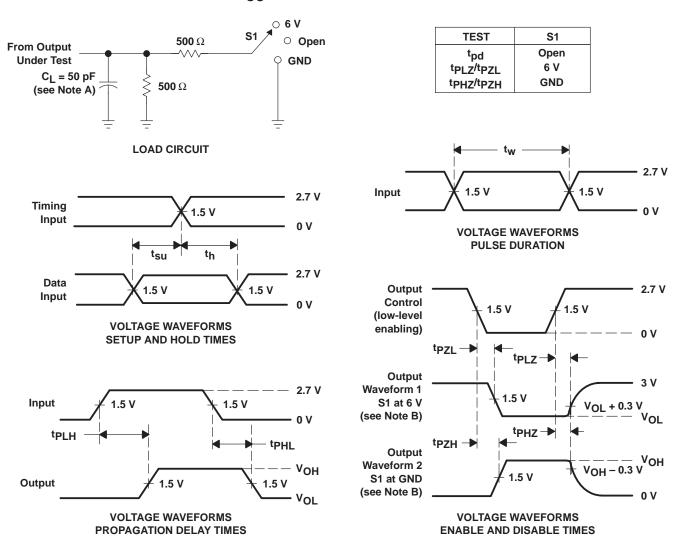
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z  $_{O}$  = 50  $\Omega$ , t  $_{f}\leq$  2 ns, t  $_{f}\leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzl and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 3. Load Circuit and Voltage Waveforms

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